

L Number	Hits	Search Text	DB	Time stamp
1	1	5862275.pn.	USPAT	2003/04/14 13:01
2	1	5862275.pn. and mold\$	USPAT	2003/04/14 13:03
3	1	(5862275.pn. and mold\$) and resin	USPAT	2003/04/14 13:18
4	265	photosetting adj1 resin	USPAT	2003/04/14 13:31
5	4	(photosetting adj1 resin) and (organic adj1 resin)	USPAT	2003/04/14 13:32
6	3505	photosensitive adj1 resin	USPAT	2003/04/14 13:21
7	1331	(photosensitive adj1 resin) and optic\$2	USPAT	2003/04/14 13:21
8	174	((photosensitive adj1 resin) and optic\$2) and molding	USPAT	2003/04/14 13:22
9	157	(photosetting adj1 resin) and optic\$2	USPAT	2003/04/14 13:26
10	4	(photosetting adj1 resin) and (organic adj1 resin\$1)	USPAT	2003/04/14 14:21
13	1	(micromachine and manufacturing).ti.	USPAT; US-PGPUB	2003/04/14 14:22
19	1	5862275.pn.	USPAT; US-PGPUB	2003/04/14 14:32
20	1	5862275.pn. and cur\$3	USPAT; US-PGPUB	2003/04/14 14:41
22	71	(photosetting adj1 resin) and silicone	USPAT; US-PGPUB	2003/04/14 14:42
23	20	(photosetting adj1 resin) with silicone	USPAT; US-PGPUB	2003/04/14 14:51
24	1	5862275.pn. and metal\$4	USPAT; US-PGPUB	2003/04/14 14:55
26	16	uejima-shunji.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 14:58
27	2282	(mold\$3 and (modulator or actuator)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 14:59
28	6	((mold\$3 and (modulator or actuator)).ab.) and (mems or micromachine\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 15:08
29	2	5862275.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 15:08